

WHAT IS CLAIMED IS:

1. A method of manufacturing a mini-card with a semiconductor memory device comprising the steps of:

5 providing an array of substrates including a plurality of individual substrates connected together;

mounting a semiconductor memory device on each of the individual substrates;

covering the individual substrates with respective cases;

10 dividing the substrate array to provide encased individual substrates each completing a mini-card having the semiconductor memory device embedded therein.

15 *Sub A1* 2. The method of manufacturing a mini-card with a semiconductor memory device according to claim 1, wherein, during the covering step, each substrate is sandwiched between top and bottom case segments.

20 *Sub B1* 3. The method of manufacturing a mini-card with a semiconductor memory device according to claim 1, wherein, during the covering step, each substrate is molded into case.

4. A mini-card with a semiconductor memory device is characterized in that the mini-card is manufactured by the method of according to claim 1.

25 5. A mini-card with a semiconductor memory device comprising:

a substrate; and

20 *Sub D1* a semiconductor memory device mounted on the substrate covered with a case;

wherein the substrate is partially exposed outwardly of the case.